

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------------------------------------------------------|------------------|
| 41 | 241 | (wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/23 10:34 |
| 42 | 241 | (wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or ("BGA")) and semiconductor and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/23 10:35 |
| 43 | 1 | ((wafer same (metal adj (film or layer)) same (attach\$5 or bond\$4) same ((balls adj grid adj arrays) or ("BGA")) same semiconductor same (dic\$4 or cut\$4 or separat\$5))) and @ad<=20000616 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/23 10:36 |
| - | 348 | (438/15).CCLS. | USPAT | 2003/05/20 07:57 |
| - | 258 | (438/113).CCLS. | USPAT | 2002/07/03 08:58 |
| - | 94 | (438/110).CCLS. | USPAT | 2002/07/03 08:58 |
| - | 59 | (438/114).CCLS. | USPAT | 2002/07/03 08:58 |
| - | 681 | 438/15,110,113,114.ccls. | USPAT | 2002/12/19 14:38 |
| - | 401 | 438/15,110,113,114.ccls. and test\$3 | USPAT | 2001/08/07 15:09 |
| - | 272 | (438/15,110,113,114.ccls. and test\$3) and (dice\$4 or cut\$5) | USPAT | 2001/08/07 15:10 |
| - | 901 | 438/15,110,113,114.ccls. | USPAT; EPO; JPO; DERWENT | 2002/02/04 09:53 |
| - | 460 | 438/15,110,113,114.ccls. and test\$3 | USPAT; EPO; JPO; DERWENT | 2002/02/04 09:54 |
| - | 325 | (438/15,110,113,114.ccls. and test\$3) and (dic\$5 or cut\$5) | USPAT; EPO; JPO; DERWENT | 2002/02/05 08:26 |
| - | 5 | ((("6077757") or ("6335224") or ("6309943") or ("6309909") or ("6326697"))).PN. | USPAT | 2003/05/21 08:46 |
| - | 7 | ((("6077757") or ("6335224") or ("6309943") or ("6309909") or ("6326697") or ("5858815") or ("5137836"))).PN. | USPAT | 2002/02/05 09:49 |
| - | 326 | (438/15,110,113,114.ccls. and test\$3) and (dic\$5 or cut\$5) | USPAT; EPO; JPO; DERWENT | 2002/02/05 08:28 |
| - | 0 | ((438/15,110,113,114.ccls. and test\$3) and (dic\$5 or cut\$5)) and (magnet\$7 adj align\$5) | USPAT; EPO; JPO; DERWENT | 2002/02/05 08:33 |
| - | 170 | ((438/15,110,113,114.ccls. and test\$3) and (dic\$5 or cut\$5)) and (align\$5) | USPAT; EPO; JPO; DERWENT | 2002/02/05 08:32 |
| - | 2705 | magnet\$7 adj align\$5 | USPAT; EPO; JPO; DERWENT | 2002/02/05 08:56 |
| - | 0 | (magnet\$7 adj align\$5) and (wafer adj20 dielectric adj tape) | USPAT; EPO; JPO; DERWENT | 2002/02/05 08:37 |
| - | 0 | wafer adj20 dielectric adj tape | USPAT; EPO; JPO; DERWENT | 2002/02/05 08:37 |
| - | 0 | wafer adj dielectric adj tape | USPAT; EPO; JPO; DERWENT | 2002/02/05 08:38 |
| - | 248 | (magnet\$7 adj align\$5) and semiconductor | USPAT; EPO; JPO; DERWENT | 2002/02/05 08:57 |
| - | 0 | ((magnet\$7 adj align\$5) and ring) and (charged adj slot) | USPAT; EPO; JPO; DERWENT | 2002/02/05 08:49 |
| - | 0 | (magnet\$7 adj align\$5) and (charged adj slot) | USPAT; EPO; JPO; DERWENT | 2002/02/05 08:49 |
| - | 613 | (magnet\$7 adj align\$5) and ring | USPAT; EPO; JPO; DERWENT | 2002/02/05 08:50 |

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| - | 47 | ((magnet\$7 adj align\$5) and ring) and semiconductor | USPAT; EPO; JPO; DERWENT | 2002/02/05 08:51 |
| - | 3066 | optically adj align\$5 | USPAT; EPO; JPO; DERWENT | 2002/02/05 08:56 |
| - | 612 | (optically adj align\$5) and semiconductor | USPAT; EPO; JPO; DERWENT | 2002/02/05 08:57 |
| - | 8 | ((("6077757") or ("6335224") or ("6309943") or ("6309909") or ("6326697") or ("5858815") or ("5137836") or ("4781969")).PN. | USPAT | 2003/06/02 08:10 |
| - | 10260 | wood.inv. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/03 08:13 |
| - | 539 | wood.inv. and alan | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/03 08:13 |
| - | 232 | (wood.inv. and alan) and (micron adj technology) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/07/03 08:14 |
| - | 1 | ("6268650").PN. | USPAT | 2002/12/20 10:24 |
| - | 425 | (438/15).CCLS. | USPAT | 2002/07/08 08:43 |
| - | 331 | (438/113).CCLS. | USPAT | 2002/07/08 08:57 |
| - | 140 | (438/110).CCLS. | USPAT | 2002/07/08 08:57 |
| - | 90 | (438/114).CCLS. | USPAT | 2002/07/08 08:57 |
| - | 425 | (438/15).CCLS. | USPAT | 2002/07/08 08:43 |
| - | 331 | (438/113).CCLS. | USPAT | 2002/07/08 08:57 |
| - | 140 | (438/110).CCLS. | USPAT | 2002/07/08 08:57 |
| - | 90 | (438/114).CCLS. | USPAT | 2002/07/08 14:32 |
| - | 13 | ((("6389689") or ("5977629") or ("5796170") or ("6326700") or ("6268650") or ("5858815") or ("5817535") or ("5770032") or ("4781969") or ("5073840") or ("5696033") or ("5834839") or ("6160714")).PN. | USPAT | 2002/07/08 10:35 |
| - | 8 | ((("6309909") or ("5858815") or ("5137836") or ("6077757") or ("6326697") or ("6165885") or ("5834320") or ("4781969")).PN. | USPAT | 2002/07/09 09:56 |
| - | 0 | (wafer adj (bond\$3 or attach\$3) near4 (dielectric adj (layer or film))) same test\$3 same (cut\$4 or dic\$3 or separat\$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/12/19 15:00 |
| - | 0 | (wafer adj (bond\$3 or attach\$3) near4 (dielectric adj (layer or film))) same test\$3 same (cut\$4 or dic\$3 or separat\$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/12/19 14:07 |
| - | 19 | wafer adj (bond\$3 or attach\$3) near4 (dielectric adj (layer or film)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/12/19 14:07 |
| - | 0 | (wafer adj (bond\$3 or attach\$3) near4 (dielectric adj (layer or film))) same test\$3 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/12/19 14:38 |
| - | 963 | 438/15,110,113,114.ccls. | USPAT | 2002/12/19 14:38 |

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|---|------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------------------------------------------------------|------------------|
| - | 1212 | 438/15,110,113,114.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/12/19 14:38 |
| - | 0 | 438/15,110,113,114.ccls. and ((wafer adj (bond\$3 or attach\$3) near4 (dielectric adj (layer or film))) same test\$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/12/19 14:40 |
| - | 9 | (wafer adj (dielectric adj (layer or film))) same test\$3 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/12/20 08:18 |
| - | 13 | ((("5834839") or ("6389689") or ("6160714") or ("5977629") or ("6326700") or ("6268650") or ("5858815") or ("5817535") or ("5770032") or ("5796170") or ("4781969") or ("5073840") or ("5696033")).PN. | USPAT | 2002/12/19 15:19 |
| - | 85 | wafer same dielectric same test\$3 same (cut\$3 or dic\$3 or slic\$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/12/20 08:42 |
| - | 78 | (wafer same dielectric same test\$3 same (cut\$3 or dic\$3 or slic\$3)) and semiconductor | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/12/20 09:38 |
| - | 348 | (wafer same (dielectric adj (layer or film))) same test\$3 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/12/20 09:35 |
| - | 322 | ((wafer same (dielectric adj (layer or film))) same test\$3) and semiconductor | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/12/20 09:38 |
| - | 98 | ((wafer same (dielectric adj (layer or film))) same test\$3) and semiconductor) and (cut\$3 or dic\$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2002/12/20 09:39 |
| - | 1 | ("6424023").PN. | USPAT | 2002/12/20 10:24 |
| - | 3 | ((("5897337") or ("5858815") or ("6389689")).PN. | USPAT | 2002/12/23 11:53 |
| - | 2 | ((("5897337") or ("6389689")).PN. | USPAT | 2002/12/23 11:53 |
| - | 9187 | ((balls adj grid adj arrays) or (BGA)) and semiconductor | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/20 07:59 |
| - | 4418 | ((balls adj grid adj arrays) or (BGA)) and semiconductor) and (dic\$4 or cut\$4 or separat\$5) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/20 08:02 |
| - | 4476 | ((balls adj grid adj arrays) or (BGA)) and semiconductor) and (dic\$4 or cut\$4 or separat\$5 or saw\$4) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/20 08:04 |
| - | 955 | ((balls adj grid adj arrays) or (BGA)) and semiconductor) and (dic\$4 or cut\$4 or separat\$5)) and (metal adj (film or layer)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/20 08:04 |

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| - | 970 | (((((balls adj grid adj arrays) or (BGA)) and semiconductor) and (dic\$4 or cut\$4 or separat\$5 or saw\$4)) and (metal adj (film or layer))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/20 08:04 |
| - | 1 | ("20010052642").PN. | US-PGPUB | 2003/05/20 08:12 |
| - | 472 | wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or separat\$5) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/20 08:52 |
| - | 233 | (wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/10/23 10:34 |
| - | 212 | ((wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616) and (dic\$5 or cut\$6 or saw\$5) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/21 08:23 |
| - | 206 | ((wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616) and (dic\$5 or cut\$6) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/20 09:06 |
| - | 1 | ((wafer adj semiconductor) same (metal adj (film or layer)) same (attach\$5 or bond\$4) same ((balls adj grid adj arrays) or (BGA)) same (dic\$4 or cut\$4 or separat\$5)) same (dic\$5 or cut\$6 or saw\$5)) and @ad<=20000616 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/20 10:06 |
| - | 212 | ((wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616) and (dic\$5 or cut\$6 or saw\$5) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/21 09:00 |
| - | 172 | ((wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616) and (dic\$5 or cut\$6 or saw\$5)) and dic\$5 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/21 09:24 |
| - | 92 | ((wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616) and (dic\$5 or cut\$6 or saw\$5)) and (dicing or diced) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/21 09:35 |
| - | 70 | ((wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616) and (dic\$5 or cut\$6 or saw\$5)) and (dicing or diced)) and (individual\$3 or each) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/21 09:36 |
| - | 70 | ((wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616) and (dic\$5 or cut\$6 or saw\$5)) and (dicing or diced)) and (individual\$3) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/21 09:36 |

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| - | 6 | (((wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616) and (dic\$5 or cut\$6 or saw\$5)) and (dicing or diced)) and (individual\$3 adj device) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/21 09:37 |
| - | 2 | ("6344401") or ("6566745")).PN. | USPAT | 2003/06/02 09:37 |